

Overview

HP EliteBook 745 G6 Notebook PC



Left

- | | |
|---|---|
| 1. HD and IR Camera (Optional) | 7. Clickpad |
| 2. Ambient Light Sensor (Optional) | 8. Smartcard Reader (Optional) |
| 3. IR Camera LEDs (Optional) | 9. USB 3.2 Gen 1 Charging Port |
| 4. Internal Microphones | 10. Vents |
| 5. HP Privacy Camera Shutter | 11. Nano Security Lock Slot (Lock sold separately) |
| 6. HD Camera LED | 12. Power Button |

Overview



Right

- | | |
|-----------------------------------|--|
| 1. Power Connector | 6. USB 3.2 Gen 1 Port |
| 2. USB Type-C™ | 7. Audio Combo Jack |
| 3. Docking Connector | 8. SIM Card Slot¹ |
| 4. Ethernet Port | 9. Touch Fingerprint Sensor (Optional) |
| 5. HDMI Port (Cable not included) | 10. Pointstick |

1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug

Overview

AT A GLANCE

- Eye-catching Ultraslim design, premium precision-crafted machined aluminum (CNC), seamless formed aluminum chassis for clean, crisp, premium look and feel
- Choice of 2nd Generation AMD Ryzen™ PRO processors
- Designed to support all HP docking options including HP's traditional Ultraslim mechanical dock and all-new Thunderbolt™ dock.¹ The 745 notebooks connect to the Thunderbolt docks via USB-C alt-mode.
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360 degree mic pick-up allows everyone to clearly hear and be heard
- Optional ant-glare touch displays with ambient light sensor
- Choice of displays:
 - 35.6 cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch 250 nits, 45% NTSC
 - 35.6 cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch 400 nits, 72% NTSC
 - 35.6cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch 1000 nits, 72% NTSC with HP Sure View⁶
 - 35.6cm (14.0") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 250 cd/m², 45% NTSC
- Enterprise grade security with HP SureStart, HP Privacy Camera¹, HP Sure View⁴, HP Sure Run, HP Sure Recover, HP Sure Click, HP Sure Sense⁵, SmartCard Reader¹ and Touch Fingerprint reader¹
- Preinstalled with Windows 10 versions or FreeDOS
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles²
- Enables AMD Memory Guard to help defend against cold boot attacks with real-time encryption and decryption of system's memory
- Flexible wireless connectivity options
- Passed MIL-STD 810G tests³
- Battery Life up to 14 hours and 45 minutes (2nd Gen AMD® Ryzen™ PRO APU processor, 14" 400 nits panel and 3-cell 50Whr battery)

1. Sold separately or as an optional feature.

2. HP Elite notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

3. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

4. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape. Available in Q3' 19.

5. HP Sure Sense requires Windows 10. See product specifications for availability.

6. Touch-enabled display and Sure View privacy panel will lower actual brightness

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

PRODUCT NAME

HP EliteBook 745 G6 Notebook PC

OPERATING SYSTEM

Preinstalled

Windows 10 Pro 64¹
Windows 10 Pro 64 (National Academic License)²
Windows 10 Home 64¹
Windows 10 Home Single Language 64¹
Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)¹
FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com/>.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see <https://aka.ms/ProEducation> for Windows 10 Pro Education feature information.

PROCESSORS

AMD Ryzen™ 7 PRO 3700U APU with Radeon™ Vega 10 Graphics (2.3 GHz base clock, up to 4 GHz max boost clock, 4 MB L3 cache, 4 cores)^{3,4,5}

AMD Ryzen™ 5 PRO 3500U APU with Radeon™ Vega 8 Graphics (2.1 GHz base clock, up to 3.7 GHz max boost clock, 4 MB L3 cache, 4 cores)^{3,4,5}

AMD Ryzen™ 3 PRO 3300U APU with Radeon™ Vega 6 Graphics (2.1 GHz base clock, up to 3.5 GHz max boost clock, 4 MB L3 cache, 4 cores)^{3,4,5}

Processor Family

2nd Generation AMD® Ryzen™ PRO APU processor⁶

3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.

5. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

CHIPSET

Chipset is integrated with processor

Features

GRAPHICS

Integrated

AMD Radeon™ Vega Graphics⁷

Supports

Support HD decode, DX12, and HDMI 2.0

7. HD content required to view HD images.

DISPLAY

Non-Touch

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC for WWAN (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera for WWAN (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera for WWAN (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD+IR camera (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080)^{7, 9, 10}

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 1000 nits with HP Sure View G3 Integrated Privacy Screen, 72% NTSC, with Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080)^{7, 8, 9, 10, 46}

35.56 cm (14") diagonal FHD, IPS, anti-glare, WLED-backlit, eDP + PSR with HP Sure View Gen2 integrated privacy screen, 700 nits, 72% NTSC (1920 x 1080)^{7, 8, 9, 10, 46}

Touch

35.56 cm (14") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC with HD+IR camera (1920 x 1080)^{7, 9, 10}

35.56 cm (14") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC with HD+IR camera for WWAN (1920 x 1080)^{7, 9, 10}

HDMI 2.0

Support resolution up to 4k @ 60Hz

7. HD content required to view HD images.

8. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation. Available in Q3' 19.

9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

10. Sold separately or as an optional feature

46. Touch-enabled display and Sure View privacy panel will lower actual brightness

Features

<i>Docking station model</i>	<i>Total number of supported displays (incl. the notebook display)</i>	<i>Max.resolutions supported</i>	<i>Dock Connectors</i>	<i>Technical limitations</i>
HP UltraSlim Docking Station	4	Dual 2.5K @ 60Hz	2xDP, 1xVGA	Dual 2.5k only with both displays into DP
HP Thunderbolt Dock G2	4	Dual 2560 x 1600 @ 60Hz Single 3840 x 2160 @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	
HP Elite USB-C Dock G4	4	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary M.2 Storage

128 GB SATA-3 SS TLC¹¹

256 GB PCIe® NVMe™ Value SS TLC¹¹

256 GB PCIe® Gen3x4 NVMe™ SS TLC¹¹

256 GB SATA-3 TLC Opal 2¹¹

512 GB PCIe® Gen3x4 NVMe™ SS TLC¹¹

512 GB PCIe® Gen3x4 NVMe™ SS TLC Opal 2¹¹

512 GB PCIe® Value¹¹

1 TB PCIe® Gen3 x4 NVMe™ SS TLC¹¹

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory

32 GB DDR4-2400 SDRAM

Memory

32 GB DDR4-2400 SDRAM (2 X 16 GB)¹²

16 GB DDR4-2400 SDRAM (1 X 16 GB)¹²

16 GB DDR4-2400 SDRAM (2 X 8 GB)¹²

8 GB DDR4-2400 SDRAM (1 x 8 GB)¹²

8 GB DDR4-2400 SDRAM (2 x 4 GB)¹²

Features

4 GB DDR4-2400 SDRAM (1 x 4 GB)¹²

Memory Slots

2 SODIMM

Both slots are customer accessible / upgradeable

DDR4 SODIMMS, system runs at 2400

Supports Dual Channel Memory

12. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AC 9260 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro™¹³

Intel® AX200 Wi-Fi 6¹⁷ (2x2) and Bluetooth® 5 Combo, non-vPro™ (supporting gigabit file transfer speeds)

Realtek RTL8822BE 802.11ac (2x2) and Bluetooth® 4.2 Combo¹³

WWAN

Intel® XMM™ 7360 LTE-Advanced Cat 9¹⁴

NFC

NXP NPC300 Near Field Communication Module

Miracast

Native Miracast Support¹⁵

Ethernet

Realtek PCIe GbE Family Controller 10/100/1000¹⁶

13. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

14. WWAN module requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

15. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

16. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

17. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen

Integrated 3 Multi Array Microphone

Features

2 Integrated Stereo Speakers (74dB)

Camera

720p HD camera^{7,10}

720p HD+IR camera^{7, 10, 18}

Sensors

Ambient light sensor (Select models only)

Hall Sensor

7. HD content required to view HD images.

10. Sold separately or as an optional feature.

18. Internet access required.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Collaboration Keyboard, spill resistant with drain

Backlit keyboard available as an option

Pointing Device

Clickpad with multi-touch gestures enabled, taps enabled as default

Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - numlk

F11 - Wireless

F12 - Calendar

Share/Present

Call Answer

Call End

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

Fn+E - Insert

Fn + W - Pause

Features

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen5¹⁹

HP Drive Lock & Automatic Drive Lock²⁰

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase²¹

Absolute Persistence Module²²

Pre-boot Authentication

Software

HP Native Miracast Support²³

HP Connection Optimizer

HP Image Assistant

HP Hotkey Support

HP JumpStart

HP Support Assistant²⁴

HP Noise Cancellation Software

Buy Office (sold separately)

Manageability Features

HP Driver Packs²⁵

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen3²⁶

HP Cloud Recovery²⁷

Client Security Software

HP Client Security Manager Gen5²⁸

HP Fingerprint Sensor²⁹

HP Power On Authentication

Windows Defender³⁰

Security Management

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³¹

SATA 0,1 port disablement (via BIOS)

USB enable/disable (via BIOS)

Power-on password (via BIOS)

Features

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Click³²

HP Sure Start For AMD³³

Sure Run Gen2³⁴

Sure Recover Gen2³⁵

Sure Sense³⁶

Security

TPM

Model: Infineon SLB9670

Version: 7.85

Revision: TPM 2.0

FIPS 140-2 Compliant: Yes (select models only)

Smartcard Reader

Model number: Alcor AU9560

FIPS 201 Compliant: Yes

IPv6 Certification:

Yes/No

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to <http://hp.com/support>, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field

Graphics (Intel Video Driver): TBD

WWAN: TBD

WLAN: TBD

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

19. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

20. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

21. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

22. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: <http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

23. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

Features

- 24. HP Support Assistant requires Windows and Internet access.
 - 25. HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.
 - 26. HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.
 - 27. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: <https://support.hp.com/us-en/document/c05115630>
 - 28. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
 - 29. HP Fingerprint Sensor sold separately or as an optional feature.
 - 30. Windows Defender Opt in and internet connection required for updates.
 - 31. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).re TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
 - 32. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
 - 33. HP Sure Start for AMD is available on select HP PCs with AMD processors. See product specifications for availability.
 - 34. HP Sure Run Gen2: See product specifications for availability.
 - 35. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
 - 36. HP Sure Sense requires Windows 10. See product specifications for availability.
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Features

POWER

Power Supply

HP Smart 45 W External AC power adapter³⁷
HP Smart 45 W External AC power adapter, 2-prong (Japan only)³⁷
HP Smart 65 W External AC power adapter³⁷
HP Smart 65 W EM External AC power adapter³⁷
45 W USB Type-C™ adapter³⁷
65 W USB Type-C™ adapter³⁷

Primary Battery

HP Long Life 3-cell, 50 Wh Li-ion^{38,39}
Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter)^{38,39}

Battery Life

Battery Life up to 14 hours and 45 minutes (2nd Gen AMD® Ryzen™ PRO APU processor, 14" 400 nits panel and 3-cell 50WHr battery)⁴⁰

Power Cord

2-wire plug - 1.0m³⁷
3-wire plug - 1.0m³⁷
3-wire plug - 1.8m³⁷
Duckhead power cord - 1.0m³⁷
Duckhead power cord - 1.8m³⁷

37. Availability may vary by country.

38. Battery is internal and not replaceable by customer. Serviceable by warranty.

39. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

40. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <http://www.bapco.com> for additional details.

WEIGHTS & DIMENSIONS

Product Weight

Starting at 3.27 lbs (non-touch); Starting at 3.32 lbs (touch)⁴¹
Starting at 1.48 kg (non-touch); Starting at 1.51 kg (touch)⁴¹

Product Dimensions (w x d x h)

Non-Touch

12.84 x 9.22 x 0.7 in
32.6 x 23.43 x 1.79 cm

Touch

12.84 x 9.22 x 0.71 in
32.6 x 23.43 x 1.81 cm

41. Weight will vary by configuration.

Features

PORTS/SLOTS

Ports

- 1 USB Type-C™ (Alt Mode)
- 2 USB 3.2 Gen 1 (1 charging)
- 1 HDMI 2.0⁴²
- 1 RJ-45 / Ethernet
- 1 Docking connector
- 1 Headphone/microphone combo
- 1 AC power
- 1 SIM card slot¹⁶
- 1 Smartcard reader¹⁶

16. Sold as an optional feature.
42. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year or 3- year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.⁴³

43. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <http://www.hp.com/go/cpc>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19V
	Average Operating Power	Win 10
	Integrated Graphics	AMD has no this data (APU is 15W)
Temperature	Max Operating Power	UMA < 45W
	Operating	32° to 95° F (0° to 35° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard Certifications	UL	Yes
	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR®	Yes, Select models ⁴⁴
	EPEAT® 2019	Yes, Silver in U.S. ⁴⁵
	Australia / NZ A-Tick Compliance	Yes
	CCC	Yes
	Japan VCCI Compliance	Yes
	KC	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	GOST	Yes
	Saudi Arabian Compliance (ICCP)	Yes
	UKRSERTCOMPUTER	Yes

44. Configurations of the HP Elitebook 745 G6 that are ENERGY STAR® certified are identified as HP Elitebook 745 G6 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

45. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit <http://www.epeat.net> for more information.

Technical Specifications

ENVIRONMENTAL & INDUSTRY

Environmental Data	Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT® Silver registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified Edge • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label* 		
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.		
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
	Normal Operation (Sort idle)	5.77 W	5.77 W	5.04 W
	Normal Operation (Long idle)	4.45 W	3.37 W	4.52 W
	Sleep	0.62 W	0.89 W	0.66 W
	Off	<p>0.44 W</p> <p>Note:</p> <p>Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		

Technical Specifications

	<i>Heat Dissipation*</i>	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
	Normal Operation (Short idle)	19.73 BTU/hr	19.73 BTU/hr	17.24 BTU/hr
	Normal Operation (Long idle)	15.22 BTU/hr	11.53 BTU/hr	15.46 BTU/hr
	Sleep	2.12 BTU/hr	3.04 BTU/hr	2.26 BTU/hr
	Off	1.50 BTU/hr	1.23 BTU/hr	1.68 BTU/hr
	<p>*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>			
	<i>Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)</i>	Sound Power (L_{WAd}, bels)		Sound Pressure (L_{pAm}, decibels)
	Typically Configured – Idle	2.5		14.5
	Fixed Disk – Random writes	3.2		27.1
	Optical Drive – Sequential reads	3.3		28.7
	<i>Longevity and Upgrading</i>	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <ul style="list-style-type: none"> • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking station • 1 multi-bay II storage port • Interchangeable HDD?? <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p>		
	<i>Batteries</i>	<p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain:</p>		

Technical Specifications

		<p>Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery description: CR2032 (coin cell) / SS03050 Battery type: Lithium / Li-Ion/Li-Ion Polymer Battery description: 6-cell high capacity Lithium-Ion battery (optional 8 cell available) Battery type:</p>		
	<i>Additional Information</i>	<ul style="list-style-type: none">• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).• This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the Silver level, see http://www.epeat.net• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.• This product contains 5.69% post-consumer recycled plastic (by wt.) according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.• This product is 96.4% recycle-able when properly disposed of at end of life.		
	<i>Packaging Materials</i>	<i>External:</i>	PAPER/Corrugated	41 g
		<i>Internal:</i>	PLASTIC/EPE (Expanded Polyethylene)	68 g
			PLASTIC/Polyethylene low density - LDPE	14 g
			PLASTIC/Polypropylene - PP	4 g
		The plastic packaging material contains at least 0.8% recycled content.		
		The corrugated paper packaging materials contains at least 0.4% recycled content.		
	<i>RoHS Compliance</i>	<p>HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.</p> <p>We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.</p> <p>We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.</p> <p>To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.</p>		
	<i>Material Usage</i>	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at <a <="" a="" href="http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_</p> </td><td data-kind="></p>		

Technical Specifications

		<p>specifications.html):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Bis(2-Ethylhexyl) phthalate (DEHP) • Benzyl butyl phthalate (BBP) • Dibutyl phthalate (DBP) • Diisobutyl phthalate (DIBP) • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBT0)
	Packaging Usage	<p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

Technical Specifications

	<p><i>End-of-life Management and Recycling</i></p>	<p>Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p>
	<p><i>HP, Inc. Corporate Environmental Information</i></p>	<p>For more information about HP's commitment to the environment:</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates:</p> <p>http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842</p> <p>and</p> <p>http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p>

DISPLAYS

<p>Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP slim NB</p>	<table> <tr> <td><i>Outline Dimensions (W x H)</i></td><td>316.17 x 197.98 mm (max)</td></tr> <tr> <td><i>Active Area</i></td><td>309.37 x 174.02 mm (typ.)</td></tr> <tr> <td><i>Weight</i></td><td>285 g (max)</td></tr> <tr> <td><i>Diagonal Size</i></td><td>14.0 inch</td></tr> <tr> <td><i>Thickness</i></td><td>3.0 mm (max)</td></tr> <tr> <td><i>Interface</i></td><td>eDP 1.2 (2 lane)</td></tr> <tr> <td><i>Surface Treatment</i></td><td>Anti-Glare</td></tr> <tr> <td><i>Touch Enabled</i></td><td>No</td></tr> <tr> <td><i>Contrast Ratio</i></td><td>600:1 (typ.)</td></tr> <tr> <td><i>Refresh Rate</i></td><td>60 Hz</td></tr> <tr> <td><i>Brightness</i></td><td>250 nits</td></tr> <tr> <td><i>Pixel Resolution</i></td><td>1920 x 1080 (FHD)</td></tr> <tr> <td><i>Format of LCD Pixel Arrangement</i></td><td>RGB</td></tr> <tr> <td><i>Backlight</i></td><td>LED</td></tr> <tr> <td><i>Color Gamut Coverage</i></td><td>45% NTSC</td></tr> </table>	<i>Outline Dimensions (W x H)</i>	316.17 x 197.98 mm (max)	<i>Active Area</i>	309.37 x 174.02 mm (typ.)	<i>Weight</i>	285 g (max)	<i>Diagonal Size</i>	14.0 inch	<i>Thickness</i>	3.0 mm (max)	<i>Interface</i>	eDP 1.2 (2 lane)	<i>Surface Treatment</i>	Anti-Glare	<i>Touch Enabled</i>	No	<i>Contrast Ratio</i>	600:1 (typ.)	<i>Refresh Rate</i>	60 Hz	<i>Brightness</i>	250 nits	<i>Pixel Resolution</i>	1920 x 1080 (FHD)	<i>Format of LCD Pixel Arrangement</i>	RGB	<i>Backlight</i>	LED	<i>Color Gamut Coverage</i>	45% NTSC
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<i>Color Gamut Coverage</i>	45% NTSC																														

Technical Specifications

Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP slim Touch on Panel Narrow Bezel	Outline Dimensions (W x H)	316.112 x 197.98 mm (max)
	Active Area	309.37 x 174.02 mm (typ.)
	Weight	290 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm (panel side) / 3.2 mm (PCBA Side) (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare On-cell
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% NTSC
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72 percent cg 400 nits eDP 1.3+PSR slim	Outline Dimensions (W x H)	316.11 x 197.98 mm (max)
	Active Area	309.31 x 173.99 mm
	Weight	<285 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.3 + PSR (2 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	400 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	72% NTSC
	Color Depth	6 bits + Hi FRC
	Viewing Angle	UWVA 85/85/85/85

Technical Specifications

Panel LCD 14 inch diagonal FHD
(1920 x 1080) Anti-Glare WLED
UWVA 72% NTSC 700 nits eDP
1.3+PSR ultraslim Privacy

Outline Dimensions (W x H)	315.41 x 196.14 max.
Active Area	309.312 x 173.988
Weight	<225 g max.
Diagonal Size	14.0"
Thickness	3.0 mm max.
Interface	eDP 1.3 + PSR
Surface Treatment	IPS
Touch Enabled	No
Contrast Ratio	Sharing mode, 600:1 (typ.) Privacy mode, 150:1 (typ.)
Refresh Rate	120 Hz
Brightness	Sharing mode, 700 nits (typ.) Privacy mode, 350 nits (typ.)
Pixel Resolution	1920 x 1080 (FHD)
Format of LCD Pixel Arrangement	RGB strip
Backlight	LED
Color Gamut Coverage	Sharing mode, 72% Privacy mode, 60%
Color Depth	8 bits
Viewing Angle	Sharing mode, CR >10, L/R/U/D, 85/85/85/85 (typ.) Privacy mode CR>2, L/R/U/D, 50/50/85/85 (typ.)

Panel LCD 14 inch diagonal FHD
(1920 x 1080) Anti-Glare WLED
UWVA 72 percent cg 1000 nits
eDP 1.4+PSR2 flat Privacy
Narrow Bezel*

Outline Dimensions (W x H)	315.31 x 195.498 mm (max)
Active Area	309.312 x 173.988 mm (typ.)
Weight	265 g (max)
Diagonal Size	14.0 inch
Thickness	3.0 mm (max)
Interface	eDP 1.4 + PSR2 (4 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	2000:1 (typ.)
Refresh Rate	60 Hz
Brightness**	1000 nits
Pixel Resolution	1920 x 1080 (FHD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED

Technical Specifications

Color Gamut Coverage	72% NTSC
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85

* Available in Q3'19.
All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.
** Touch-enabled display and Sure View privacy panel will lower actual brightness

Technical Specifications

STORAGE

<i>SSD 128 GB 2280 M2 SATA-3 TLC</i>	<i>Form Factor</i>	M.2 2280
	<i>Capacity</i>	128 GB
	<i>NAND Type</i>	TLC
	<i>Height</i>	0.09 in (2.3 mm)
	<i>Width</i>	0.87 in (22 mm)
	<i>Weight</i>	0.02 lb (10 g)
	<i>Interface</i>	ATA-8, SATA 3.0
	<i>Maximum Sequential Read</i>	Around 540 ~ 560 MB/s
	<i>Maximum Sequential Write</i>	Around 380 ~ 530 MB/s
	<i>Logical Blocks</i>	250069680
	<i>Operating Temperature</i>	32° to 158°F (0° to 70°C) [ambient temp]
	<i>Features</i>	ATA Security; DIPM; TRIM; DEVSLP

<i>SSD 1 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided</i>	<i>Form Factor</i>	M.2 2280
	<i>Capacity</i>	1 TB
	<i>NAND Type</i>	TLC
	<i>Height</i>	0.09 in (2.3 mm)
	<i>Width</i>	0.87 in (22 mm)
	<i>Weight</i>	0.02 lb (10 g)
	<i>Interface</i>	PCIe NVMe Gen3X4
	<i>Maximum Sequential Read</i>	Around 3200 ~ 3480 MB/s
	<i>Maximum Sequential Write</i>	Around 2400 ~ 3037 MB/s
	<i>Logical Blocks</i>	2000409264
	<i>Operating Temperature</i>	32° to 158°F (0° to 70°C) [ambient temp]
	<i>Features</i>	ATA Security; TRIM; L1.2

<i>SSD 256 GB 2280 M2 PCIe-3x4 SS NVMe TLC</i>	<i>Form Factor</i>	M.2 2280
	<i>Capacity</i>	256 GB
	<i>NAND Type</i>	TLC
	<i>Height</i>	0.09 in (2.3 mm)
	<i>Width</i>	0.87 in (22 mm)
	<i>Weight</i>	0.02 lb (10 g)
	<i>Interface</i>	PCIe NVMe Gen3X4
	<i>Maximum Sequential Read</i>	Around 2900 ~ 3167 MB/s
	<i>Maximum Sequential Write</i>	Around 1300 ~ 1663 MB/s
	<i>Logical Blocks</i>	500118192
	<i>Operating Temperature</i>	32° to 158°F (0° to 70°C) [ambient temp]

Technical Specifications

	Features	ATA Security; TRIM; L1.2
SSD 256 GB 2280 M2 SATA-3 Self Encrypted OPAL2 Three Layer Cell	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Around 530 ~ 560 MB/s
	Maximum Sequential Write	Around 500 ~ 530 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP
SSD 256 GB 2280 PCIe NVMe Value	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 780 ~ 1300 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2700 ~ 3400 MB/s
	Maximum Sequential Write	Around 1390 ~ 2956 MB/s

Technical Specifications

<i>Logical Blocks</i>	1000215215
<i>Operating Temperature</i>	32° to 158°F (0° to 70°C) [ambient temp]
<i>Features</i>	ATA Security; TRIM; L1.2

SSD 512 GB 2280 PCIe NVMe Value

<i>Form Factor</i>	M.2 2280
<i>Capacity</i>	512 GB
<i>NAND Type</i>	TLC/QLC
<i>Height</i>	0.09 in (2.3 mm)
<i>Width</i>	0.87 in (22 mm)
<i>Weight</i>	0.02 lb (10 g)
<i>Interface</i>	PCIe NVMe
<i>Maximum Sequential Read</i>	Around 1500 ~ 1700 MB/s
<i>Maximum Sequential Write</i>	Around 860 ~ 1500 MB/s
<i>Logical Blocks</i>	1000215215
<i>Operating Temperature</i>	32° to 158°F (0° to 70°C) [ambient temp]
<i>Features</i>	ATA Security; TRIM; L1.2

SSD 512 GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Cell

<i>Form Factor</i>	M.2 2280
<i>Capacity</i>	512 GB
<i>NAND Type</i>	TLC
<i>Height</i>	0.09 in (2.3 mm)
<i>Width</i>	0.87 in (22 mm)
<i>Weight</i>	0.02 lb (10 g)
<i>Interface</i>	PCIe NVMe Gen3X4
<i>Maximum Sequential Read</i>	Around 2900 ~ 3400 MB/s
<i>Maximum Sequential Write</i>	Around 1000 ~ 2500 MB/s
<i>Logical Blocks</i>	1000215216
<i>Operating Temperature</i>	32° to 158°F (0° to 70°C) [ambient temp]
<i>Features</i>	ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP

Technical Specifications

NETWORKING/COMMUNICATIONS

Intel® 9260 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo ¹ Non-vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n <ul style="list-style-type: none"> • 2.402 – 2.482 GHz 802.11a/n/ac <ul style="list-style-type: none"> • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	<ul style="list-style-type: none"> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum

Technical Specifications

	<ul style="list-style-type: none"> • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)

Technical Specifications

<i>Signaling Data Rate</i>	Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps BLE: 1 Mbps signaling data rate¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
<i>Transmit Power</i>	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
<i>Power Consumption</i>	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
<i>Electrical Interface</i>	USB 2.0 compliant
<i>Bluetooth Software Supported</i>	Microsoft Windows Bluetooth Software
<i>Power Management</i>	Microsoft Windows ACPI, and USB Bus Support
<i>Certifications</i>	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
<i>Power Management Certifications</i>	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
<i>Bluetooth Profiles Supported</i>	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.

Technical Specifications

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

802.11a/b/g/n/ac (2 x 2) Wireless LAN Standards
Wi-Fi® and Bluetooth®
4.2 Combo¹

Interoperability

Frequency Band

Data Rates

Modulation

Security³

Network Architecture
Models

Roaming

Output Power²

Power Consumption

IEEE 802.11a

IEEE 802.11b

IEEE 802.11g

IEEE 802.11n

IEEE 802.11ac

Wi-Fi® certified

802.11b/g/n

• 2.402 – 2.482 GHz

802.11a/n

• 4.9 – 4.95 GHz (Japan)

• 5.15 – 5.25 GHz

• 5.25 – 5.35 GHz

• 5.47 – 5.725 GHz

• 5.825 – 5.850 GHz

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

• AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

• WPA2 certification

• IEEE 802.11i

• WAPI

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

• 802.11b : +14dBm minimum

• 802.11g : +12dBm minimum

• 802.11a : +12dBm minimum

• 802.11n HT20(2.4GHz) : +12dBm minimum

• 802.11n HT40(2.4GHz) : +12dBm minimum

• 802.11n HT20(5GHz) : +10dBm minimum

• 802.11n HT40(5GHz) : +10dBm minimum

• 802.11ac VHT80(5GHz) : +10dBm minimum

• Transmit mode 2.0 W

• Receive mode 1.6 W

Technical Specifications

- Idle mode (PSP) 180 mW (WLAN Associated)
- Idle mode 50 mW (WLAN unassociated)
- Connected Standby 10mW
- Radio disabled 8 mW

<i>Power Management</i>	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
<i>Receiver Sensitivity³</i>	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum	
<i>Antenna type</i>	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
<i>Form Factor</i>	PCI-Express M.2 MiniCard	
<i>Dimensions</i>	Type 2230 : 2.3 x 22.0 x 30.0 mm	
<i>Weight</i>	Type 2230: 2.8 g	
<i>Operating Voltage</i>	3.3v +/- 9%	
<i>Temperature</i>	<i>Operating</i>	14° to 158° F (-10° to 70° C)
	<i>Non-operating</i>	-40° to 176° F (-40° to 80° C)
<i>Humidity</i>	<i>Operating</i>	10% to 90% (non-condensing)
	<i>Non-operating</i>	5% to 95% (non-condensing)
<i>Altitude</i>	<i>Operating</i>	0 to 10,000 ft (3,048 m)
	<i>Non-operating</i>	0 to 50,000 ft (15,240 m)
<i>LED Activity</i>	LED Amber – Radio OFF	
	LED White – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

<i>Bluetooth Specification</i>	4.0/4.1/4.2 Compliant
<i>Frequency Band</i>	2402 to 2480 MHz
<i>Number of Available Channels</i>	Legacy : 0~79 (1 MHz/CH)
	BLE : 0~39 (2 MHz/CH)

Technical Specifications

<i>Signaling Data Rate</i>	Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps BLE: 1 Mbps signaling data rate¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
<i>Transmit Power</i>	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
<i>Power Consumption</i>	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
<i>Electrical Interface</i>	USB 2.0 compliant
<i>Bluetooth Software Supported</i>	Microsoft Windows Bluetooth Software
<i>Power Management</i>	Microsoft Windows ACPI, and USB Bus Support
<i>Certifications</i>	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
<i>Power Management Certifications</i>	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
<i>Bluetooth Profiles Supported</i>	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.**
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.**
- 3. Check latest software/driver release for updates on supported security features.**
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).**

Technical Specifications

Intel® Wi-Fi® 6⁵ AX200 + Wireless LAN Standards
BT5 (802.11ax 2 x 2, non-
vPro, supporting gigabit
file transfer speeds)
non-vPro

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11v

Interoperability
Frequency Band

Wi-Fi® certified
802.11b/g/n/ax
• 2.402 – 2.482 GHz
802.11a/n/ac/ax
• 4.9 – 4.95 GHz (Japan)
• 5.15 – 5.25 GHz
• 5.25 – 5.35 GHz
• 5.47 – 5.725 GHz
• 5.825 – 5.850 GHz

Data Rates

•802.11b: 1, 2, 5.5, 11 Mbps
•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
•802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)

Modulation

Direct Sequence Spread Spectrum
OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³

•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
•AES-CCMP: 128 bit in hardware
•802.1x authentication
•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
•WPA2 certification
•IEEE 802.11i
•WAPI

Network Architecture
Models
Roaming

Ad-hoc (Peer to Peer)
Infrastructure (Access Point Required)
IEEE 802.11 compliant roaming between access points

Technical Specifications

<i>Output Power²</i>	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum 	
<i>Power Consumption</i>	<ul style="list-style-type: none"> • Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW 	
<i>Power Management</i>	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
<i>Receiver Sensitivity³</i>	<p>802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum</p>	
<i>Antenna type</i>	<p>High efficiency antenna with spatial diversity, mounted in the display enclosure</p> <p>Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications</p>	
<i>Form Factor</i>	PCI-Express M.2 MiniCard	
<i>Dimensions</i>	<p>1. Type 2230: 2.3 x 22.0 x 30.0 mm</p> <p>2. Type 1216: 1.67 x 12.0 x 16.0 mm</p>	
<i>Weight</i>	<p>1. Type 2230: 2.8g</p> <p>2. Type 126: 1.3g</p>	
<i>Operating Voltage</i>	3.3v +/- 9%	
<i>Temperature</i>	<i>Operating</i>	14° to 158° F (–10° to 70° C)
	<i>Non-operating</i>	–40° to 176° F (–40° to 80° C)
<i>Humidity</i>	<i>Operating</i>	10% to 90% (non-condensing)
	<i>Non-operating</i>	5% to 95% (non-condensing)

Technical Specifications

Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps BLE: 1 Mbps signaling data rate¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Technical Specifications

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
 3. Check latest software/driver release for updates on supported security features.
 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
 5. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.
- Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final.
- If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

Intel® XMM™ 7360 LTE-Advanced CAT9¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	5.8 g
	Dimensions	42 x 30 x 2.3 mm

Technical Specifications

(Length x Width x
Thickness)

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. WWAN is an optional feature, requires factory configuration and separately purchased service contract. Check with service provider for coverage and availability in your area. 4G LTE not available on all products, in all regions.

Near Field Communications Controller (optional)	Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
	Chipset	NPC300
	System interface	I2C
	NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
	Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards
	Card Emulation (PICC-VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
Power Consumption (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)	Operating temperature	0°C to 70°C
	Storage temperature	-20°C to 125°C
	Humidity	10-90% operating 5-95% non-operating
	Supply Operating voltage	4.35 to 5.25 Volts
	I/O Voltage	1.8V or 3.3V
	Mode	Power Consumption, Typical
	Polling	710.93 mW
	Detected Test Tag Type 1	152.09 mW

Technical Specifications

<i>Detected Test Tag Type 2</i>	341.26 mW
<i>Detected Test Tag Type 3</i>	383.76 mW
<i>Detected Test Tag Type 4</i>	312.26 mW
<i>Antenna</i>	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

<i>Realtek RTK8111EPH 10/100/1000 Integrated NIC</i>	<i>Connector</i>	RJ-45
	<i>System Interface</i>	PCIe + SMBus
	<i>Data rates supported</i>	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	<i>IEEE Compliance</i>	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	<i>Performance</i>	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	<i>Power Consumption</i>	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	<i>Power Management</i>	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	<i>Management Interface</i>	Auto MDI/MDIX Crossover cable detection
	<i>IT Manageability</i>	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status

Technical Specifications

Security & Manageability **RTK DASH support with appropriate RTK chipset components**

POWER

AC Adapter 45 Watt nPFC Wall Mount USB type C Straight 1.8m C6NS	Dimensions	62.0 x 62.0 x 28.5 mm	
	Weight	unit: 220 g +/- 10 g	
Output	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 10V: 87.5% 12V: 87.8% 15V: 87.8% 20V: 87.8% 47 ~ 63Hz
		Input frequency range	47 ~ 63Hz
		Input AC current	Max. 1.4 A at 90 Vac
		Output power	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 10V: 87.5%
		DC output	5V: 81.5%
		Hold-up time	9V: 86.7%
		Output current limit	10V: 87.5%
	Connector	Non-Standard C6	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
EMI and Safety Certifications		Storage Humidity	10% to 95%
		CE Mark - full compliance with LVD and EMC directives	
		Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.	
		MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m	Dimensions	95.0 x 40.0 x 26.5 mm	
	Weight	unit: 200 g +/- 10 g	
Output	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
		Output power	45W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A

Technical Specifications

Connector	C6	
Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m 2prong	Dimensions	95.0 x 40.0 x 26.5 mm	
	Weight	unit: 200 g +/- 10 g	
	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	45W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	C8	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt nPFC USB type C Straight 1.8 m C6NS	<i>Dimensions</i>	74 x 74 x 28.5 mm	
	<i>Weight</i>	unit: 245 g +/- 10 g	
	<i>Input</i>	<i>Input Efficiency</i>	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		<i>Input frequency range</i>	47 ~ 63 Hz
		<i>Input AC current</i>	1.7 A at 90 VAC and maximum load
		<i>Output power</i>	65W
		<i>Output</i>	

Technical Specifications

	DC output	5V/9V/10V/12V/15V/20V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<8.0A
Connector	Non-Standard C6	
Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	5% to 95%
	Storage Humidity	5% to 95%
Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 100,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt
Smart nPFC EM Barrel
4.5 mm New EM

Dimensions	102 x 55 x 30 mm	
Weight	unit: 250 g +/- 10 g	
Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
	Input frequency range	47 ~ 63 Hz
	Input AC current	Max. 1.7 A at 90 Vac
	Output power	65 W
	DC output	19.5 V
Output	Hold-up time	5ms at 115 Vac input
	Output current limit	<11.0 A
	C6	
	Operating temperature	32°F to 95°F (0° to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
Environmental Design	Altitude	0 to 5,000 m
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt
Smart nPFC Standard
Barrel 4.5 mm Right
Angle 1.8 m

Dimensions	90.0 x 51 x 28.5 mm	
Weight	unit: 230 g +/- 10 g	
Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
	Input frequency range	47 ~ 63 Hz
	Input AC current	Max. 1.7 A at 90 Vac
	Output power	65 W
Output		

Technical Specifications

	DC output	19.5 V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<11.0 A
	Connector	C6
Environmental Design	4.5mm Barrel Type	
	Operating temperature	32°F to 95°F (0°to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000 m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.
Battery SS 3 Cell 50 WHr Long Life -PL	Dimensions (H x W x L)	L 278.7 mm x W 76.3 mm x H 7.1 mm
	Weight	193 +/- 10 g
	Cells/Type	3cell Lithium-Ion Polymer cell / P604883A1
	Voltage	11.55 V
Energy	Amp-hour capacity	4.113 Ah/ 4.330 Ah
	Watt-hour capacity	50 Wh
Temperature	Operating (Charging)	0° to 50° C
	Operating (Discharging)	-10° to 60° C
Warranty	based on system offering	
Optional Travel Battery Available	No	

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part #
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack	H1D24AA
	HP 17.3 Business Backpack	2SC67AA
	HP 15.6 Business Top Load	2SC66AA
Docking	HP UltraSlim Docking Station	D9Y32AA
	HP UltraSlim Docking Station TAA US	E5C22AV
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock 120W G2 TAA	2UK37AA
	HP TB Dock Audio Module	3AQ21AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Mini Dock	1PM64AA
	HP USB Travel Dock	TOK30AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP USB-C Universal Dock w/4.5mm Adapter - non-flash version	3DV65AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Slim Bluetooth Mouse to AMO	F3J92AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Essential USB Mouse	2TX37AA
	HP Elite Presenter Mouse	2CE30AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP UC Wireless Mono Headset	W3K08AA

Options and Accessories (sold separately and availability may vary by country)

	HP UC Wireless Duo Headset	W3K09AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to DP	N9K78AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to DVI	F5A28AA
	HP HDMI to VGA	H4F02AA
<i>Power</i>	HP 65W Slim AC Adapter	H6Y82AA
	HP 45W Smart AC Adapter	H6Y88AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA
<i>Storage</i>	HP USB External DVDRW Drive	F2B56AA
<i>Security</i>	HP Docking Station Cable Lock	AU656AA
	HP Essential Combination Lock	T0Y16AA
	HP Combination Lock	T0Y15AA
	HP Keyed Cable lock	T0Y14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Keyed Cable Lock	T1A64AA

Summary of Changes

<i>Date of change:</i>	<i>Version History:</i>		<i>Description of change:</i>
June 20, 2019	V1 to V2	Added	Environmental Section
June 25, 2019	V2 to V3	Updated	Color Gamut
June 27, 2019	V3 to V4	Updated	Battery Life and Display Section
September 6, 2019	V4 to V5	Updated	Nano lock slot, Storage Section and Brightness disclaimer for 1000nits
October 8, 2019	V5 to V6	Added	Enable AMD Memory in at a glance section
March 19, 2020	V6 to V7	Updated	Audio Section
April 16, 2020	V7 to V8	Updated	Display and Weight sections
May 27, 2020	V8 to V9	Updated	Ports Section

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